1. Record Nr.   UNINA9910449844603321

   Titolo   Computational modelling [[electronic resource] /] / guest editor, Chris
                     Bailey

   Pubbl/distr/stampa   Bradford, England, : Emerald Group Publishing, c2002

   ISBN   1-280-47971-X
                     9786610479719
                     1-84544-723-9

   Descrizione fisica   1 online resource (69 p.)

   Collana   Soldering & surface mount technology ; ; v.14, no. 1

   Altri autori (Persone)   BaileyChris

   Disciplina   621.381531

   Soggetti   Solder and soldering - Mathematical models
                     Surface mount technology - Mathematical models
                     Electronic books.

   Lingua di pubblicazione   Inglese

   Formato   Materiale a stampa

   Livello bibliografico   Monografia

   Note generali   Description based upon print version of record.

   Nota di contenuto   Contents; Abstracts & keywords; Editorial; Correlation of solder paste
                     rheology with computational simulations of the stencil printing
                     process; Solder paste reflow modeling; Numerical modelling of scanned
                     beam laser soldering of fine pitch packages; A simplified model of the
                     reflow soldering process; CFD modelling of the flow field inside a
                     reflow oven; Analysis on solder ball shear testing conditions with a
                     simple computational model; Optimisation modelling for flip-chip
                     solder joint reliability; Internet commentary; Book review; Industry
                     news; Appointments; International diary
                     Note from the publisher

   Sommario/riassunto   This special issue of SSMT brings together seven papersdemonstrating
                     the latest achievements in the applications ofcomputational modelling
                     technology to soldering processesand solder joint reliability.Why use
                     computational models?The performance of soldering materials during
                     productassembly is governed by complex interacting
                     physicalphenomena.